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(12) **United States Design Patent** (10) **Patent No.:** **US D900,760 S**
Kouzuma et al. (45) **Date of Patent:** **** Nov. 3, 2020**

(54) **ION SHIELD PLATE FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

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(**) Term: **15 Years**

(21) Appl. No.: **29/677,753**

(22) Filed: **Jan. 23, 2019**

(30) **Foreign Application Priority Data**

Jul. 24, 2018 (JP) 2018-016190

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184**; D26/138; D23/261; D15/126

(58) **Field of Classification Search**
USPC D13/184; D26/1, 24, 74, 72, 36, 59, 118, D26/133, 134, 261; D15/126
CPC H01R 5/00; H01R 13/46; H01R 13/514; H01R 31/02; F21V 5/00; H01J 19/54; H01J 5/48; H01J 1/02; H01J 5/16; H01J 5/00; H01J 5/50; H01L 33/642; H01L 33/643; H01L 33/644
See application file for complete search history.

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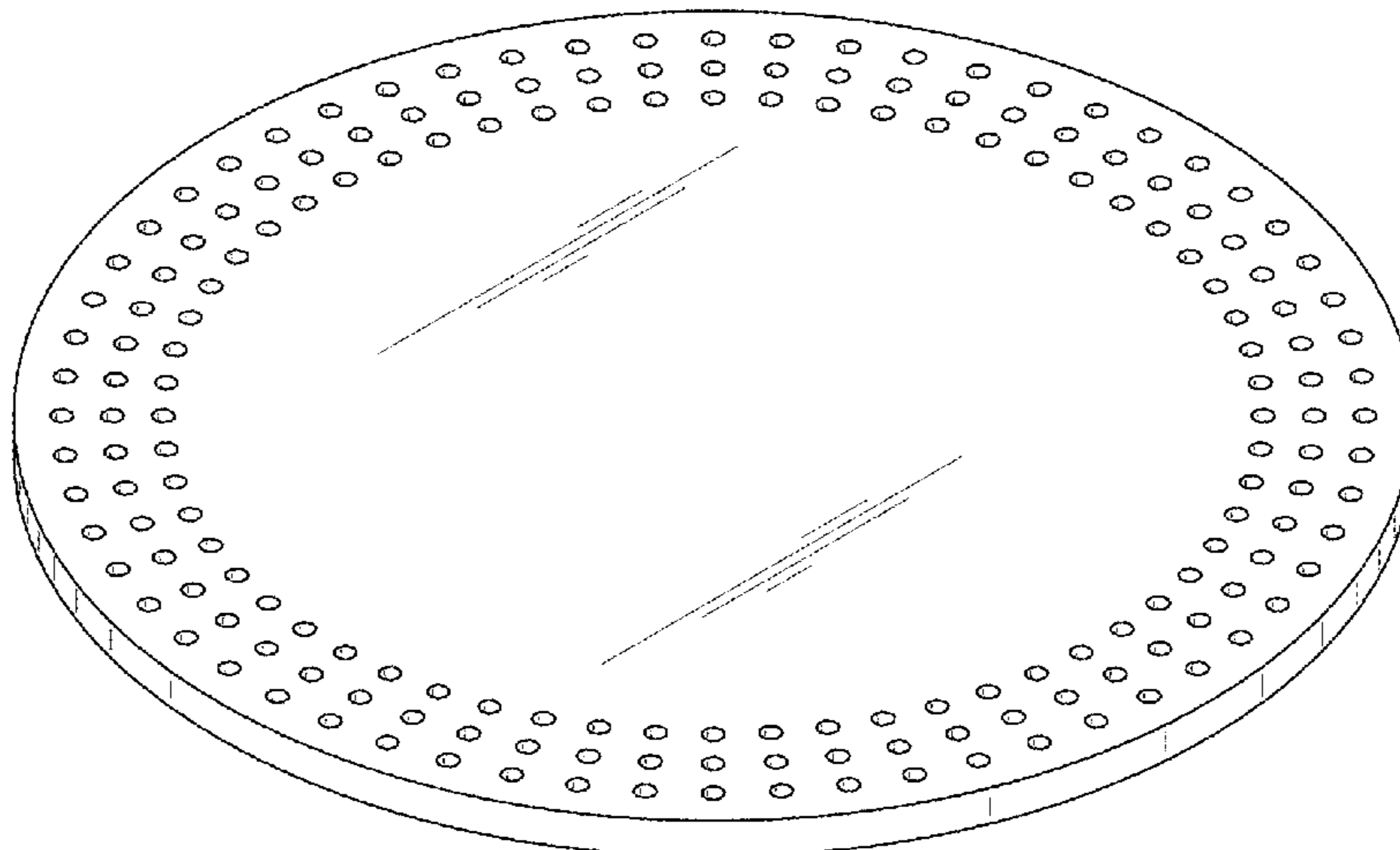
(57) **CLAIM**

The ornamental design for an ion shield plate for semiconductor manufacturing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front, bottom and right side perspective view of an ion shield plate for semiconductor manufacturing apparatus according to the design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is a rear elevational view thereof; and,
FIG. 8 is a cross-sectional view taken along line 8-8 of FIG. 2.

1 Claim, 3 Drawing Sheets



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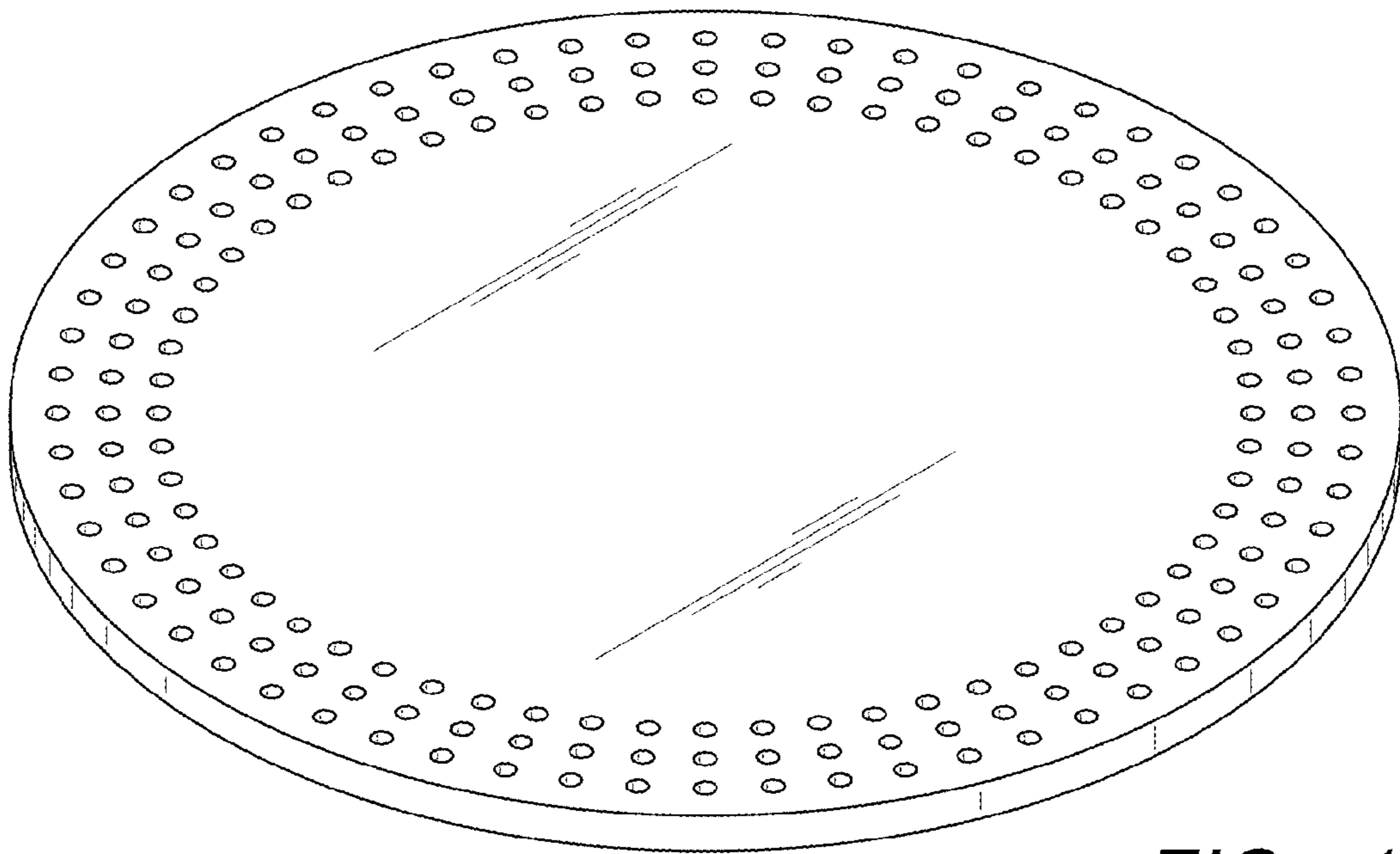


FIG. 1

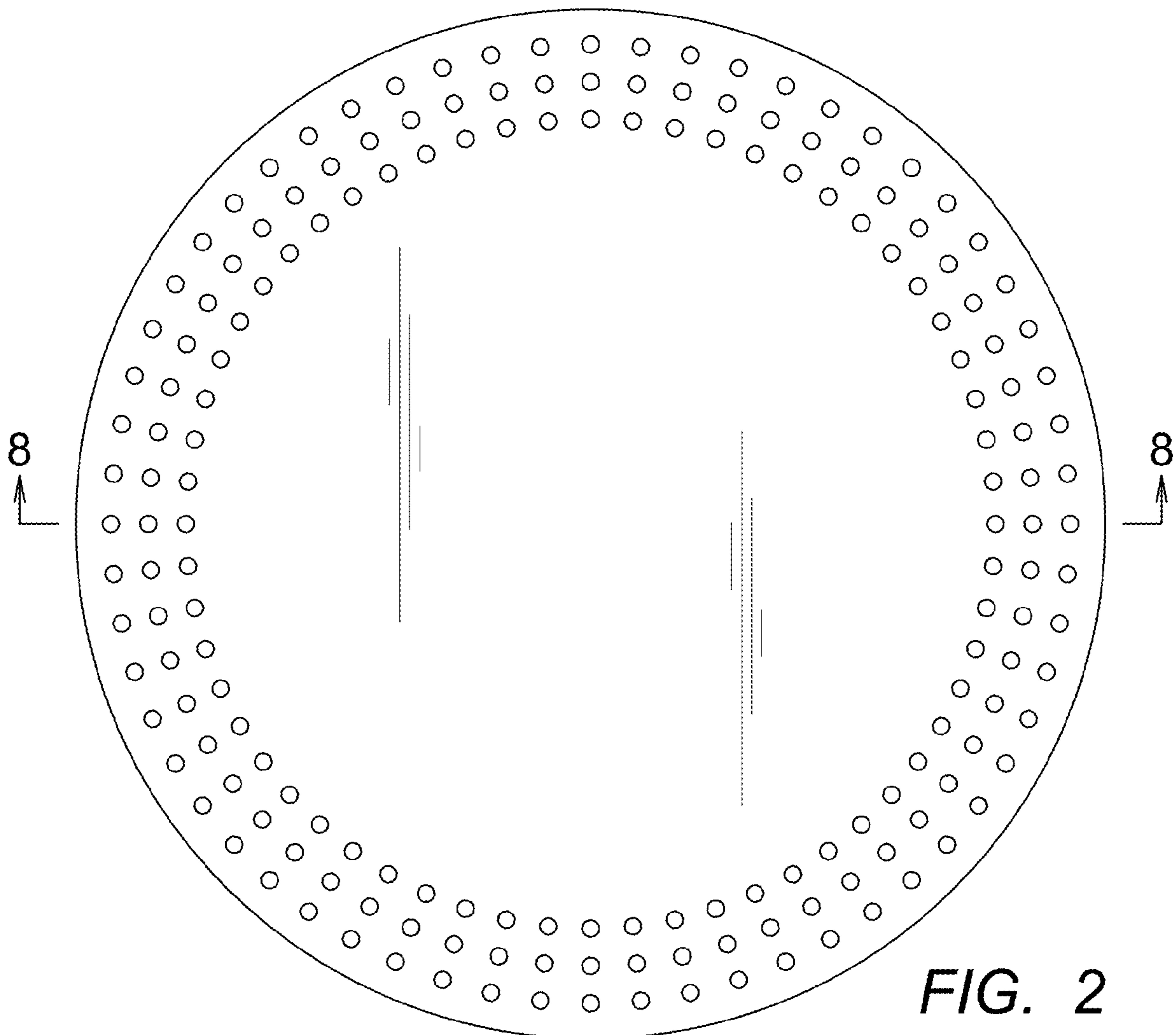


FIG. 2



FIG. 3



FIG. 4



FIG. 5

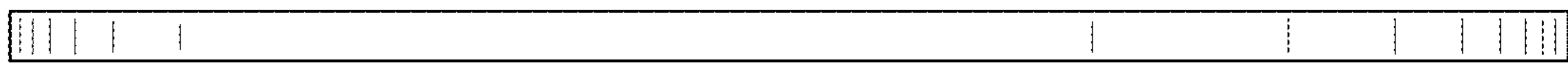


FIG. 6

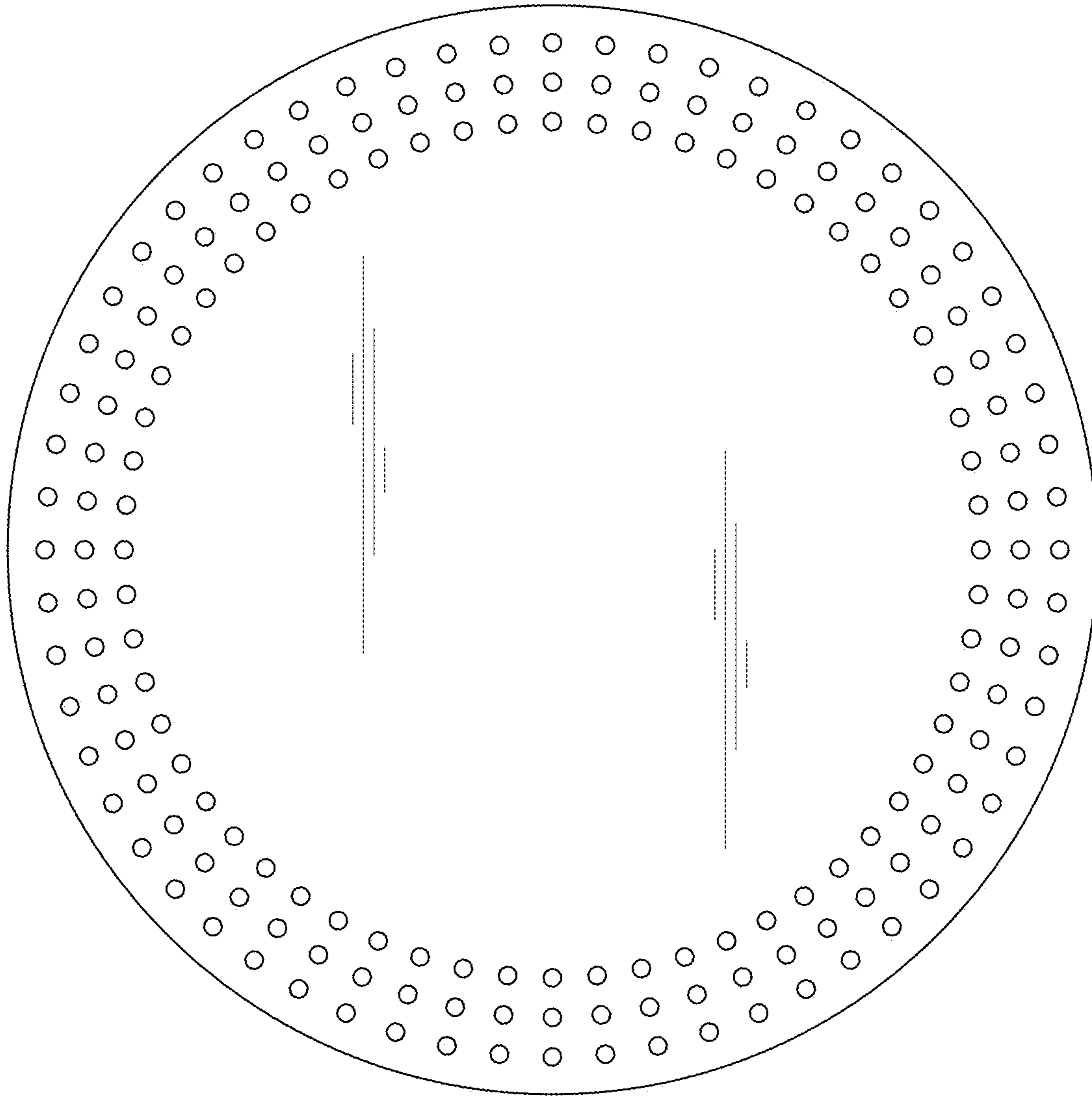


FIG. 7

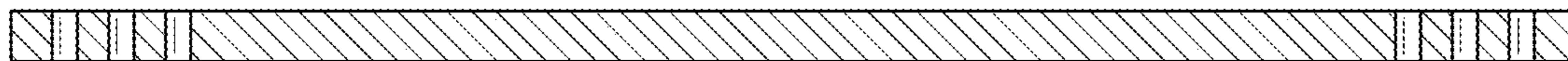


FIG. 8

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : D900,760 S
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DATED : November 3, 2020
INVENTOR(S) : Yutaka Kouzuma et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the Title Page

Item (71), should read: -- Hitachi High-Tech Corporation --.

Signed and Sealed this
Second Day of March, 2021



Drew Hirshfeld
*Performing the Functions and Duties of the
Under Secretary of Commerce for Intellectual Property and
Director of the United States Patent and Trademark Office*